

## ● 72 pin SIMM (Continued)

Memory capacity [Bit]	Bit Configuration (Word×Bit)	Power supply voltage	Load memories Bank Configuration	Package outline	Outward dimensions W×H×D (mm)	Contact Plating	Access time tRAC (ns)	Type No.				
144M	4Mx36	5V ± 10%	M5M417400CJx8 + M5M44100CJx4 2RAS/1BANK	Both sides	107.95 × 25.4 × 8.6	Au plating	60	MH4M36CXJ-6				
							70	MH4M36CXJ-7				
			Ni + Solder plating			60	MH4M36CNXJ-6					
						75	MH4M36CNXJ-7					
				M5M417405CJx8 + M5M44105CJx4 2RAS/1BANK			Au plating	60	MH4M365CXJ-6			
							70	MH4M365CXJ-7				
							Ni + Solder plating	60	MH4M365CNXJ-6			
								70	MH4M365CNXJ-7			
160M	4Mx40		M5M417400CJx10 1RAS/1CAS/1BANK	One side	107.95 × 25.4 × 5.08	Au plating	60	MH4M40CJ-6				
							70	MH4M40CJ-7				
256M	8Mx32	5V ± 10%	M5M417400CJx16 4RAS/2BANK	Both sides	107.95 × 25.4 × 8.6	Au plating	60	MH8M32CJ-6				
							70	MH8M32CJ-7				
			Ni + Solder plating			60	MH8M32CNJ-6					
						70	MH8M32CNJ-7					
				M5M417405CJx16 4RAS/2BANK			Au plating	50	MH8M325CJ-5			
							60	MH8M325CJ-6				
								70	MH8M325CJ-7			
							Ni + Solder plating	50	MH8M325CNJ-5			
							60	MH8M325CNJ-6				
							70	MH8M325CNJ-7				
288M	8Mx36	5V ± 10%	M5M417400CJx16 + M5M417500BJx2 2RAS/2BANK	Both sides	107.95 × 25.4 × 8.6	Au plating	60	MH8M36CJ-6				
							70	MH8M36CJ-7				
Ni + Solder plating	60		MH8M36CNJ-6									
	70		MH8M36CNJ-7									
320M	8Mx40		5V ± 10%	M5M417400CJx20 2RAS/2CAS/2BANK	Both sides	107.95 × 25.4 × 8.6	Au plating	60	MH8M40CJ-6			
								70	MH8M40CJ-7			
512M	16Mx32			5V ± 10%			M5M416100BJx32 2RAS/1BANK	Both sides	107.95 × 43.46 × 8.6	Au plating	60	MH16M32BJ-6
											70	MH16M32BJ-7
		Ni + Solder plating			60	MH16M32BNJ-6						
					70	MH16M32BNJ-7						
576M	16Mx36	5V ± 10%			M5M416100BJx36 2RAS/1BANK	Both sides	107.95 × 43.46 × 8.6	Au plating	60	MH16M36BJ-6		
									70	MH16M36BJ-7		
			Ni + Solder plating		60			MH16M36BNJ-6				
					70			MH16M36BNJ-7				

## ● 72 pin SO-DIMM

Memory capacity [Bit]	Bit Configuration (Word×Bit)	Power supply voltage	Load memories	Package outline	Outward dimensions W×H×D (mm)	Contact Plating	Access time tRAC (ns)	Type No.
32M	1Mx32	5V ± 10%	M5M44400CTP×8	Both sides	59.69 × 25.4 × 3.6	Au plating	50	MH1M32CJ-5
							60	MH1M32CJ-6
			70				MH1M32CJ-7	
		3.3V ± 0.3V	M5M44405CTP×8 EDO				50	MH1M325CJ-5
							60	MH1M325CJ-6
			70				MH1M325CJ-7	
64M	2Mx32	5V ± 10%	M5M417800CTP×4	One side	59.69 × 25.4 × 2.4	Au plating	60	MH2M32CJ-6
							70	MH2M32CJ-7
			3.3V ± 0.3V				M5M417805CTP×4 EDO	50
		60						MH2M325CJ-6
		70					MH2M325CJ-7	
								M5M4V17800CTP×4
					70	MH2V32CJ-7		
128M	4Mx32	5V ± 10%	M5M417400CTP×8	Both sides	59.69 × 25.4 × 3.8	Au plating	60	MH4M32CJ-6
							70	MH4M32CJ-7
			3.3V ± 0.3V				M5M417405CTP×8 EDO	50
		60						MH4M325CJ-6
		70					MH4M325CJ-7	
								M5M4V17400CTP×8
					70	MH4V32CJ-7		
			M5M4V17405CTP×8 EDO			60	MH4V325CJ-6	
						70	MH4V325CJ-7	